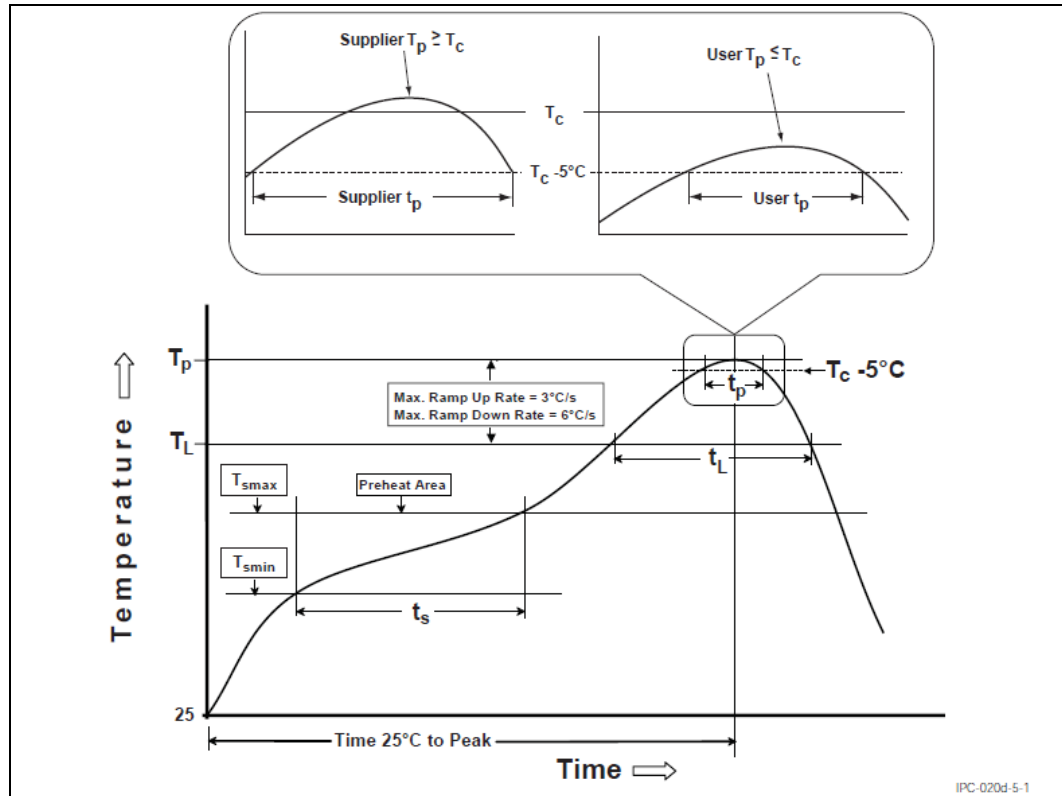


Recommended Solder Profile

The reflow profile for our products depends on the soldering material and the circuit board assembly. Also affecting the reflow profiles is the amount of solder, flux, heat transfer characteristics of the circuit board and its components, and the temperature limitations of the other components on the circuit board. API Delevan does not specify solder profiles for our products for these reasons.

A reflow profile based on the IPC/JEDEC J-STD-020 is provided as a guide.



API Delevan **RoHS** Parts Maximum Recommended Temperature and Time for reflow profile

- T_c = Max. 260°C
- t_p = Max. 10 Seconds
- Ramp-Up Rate (T_L to T_p) = 1.5°C/s min to 3.0°C/s max.
- Ramp-Down Rate (T_p to T_L) = 3.0°C/s min to 6.0°C/s max.

API Delevan **Non RoHS** Parts Maximum Recommended Temperature and Time for reflow profile

- T_c = Max. 240°C
- t_p = Max. 10 Seconds
- Ramp-Up Rate (T_L to T_p) = 1.5°C/s min to 3.0°C/s max.
- Ramp-Down Rate (T_p to T_L) = 3.0°C/s min to 6.0°C/s max.

Any deviations from these recommended rates can cause damage to the product.